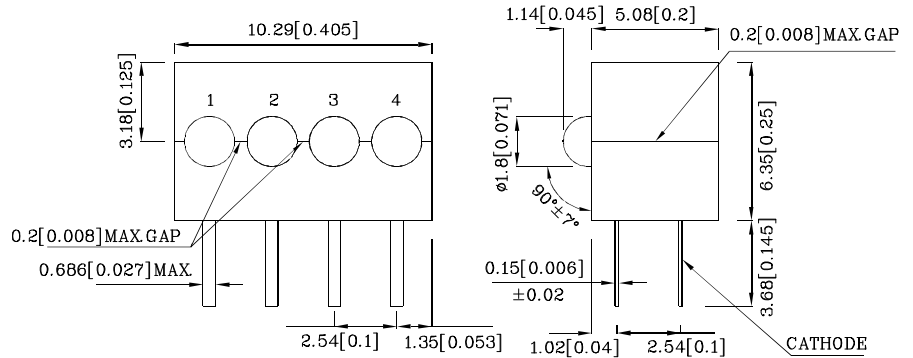


Features

- Housing material: Type 66 Nylon
- Black casing provides superior contrast
- Housing UL rating: 94V-0
- Reliable & robust
- Custom color combinations available
- RoHS Compliant



Package Schematics



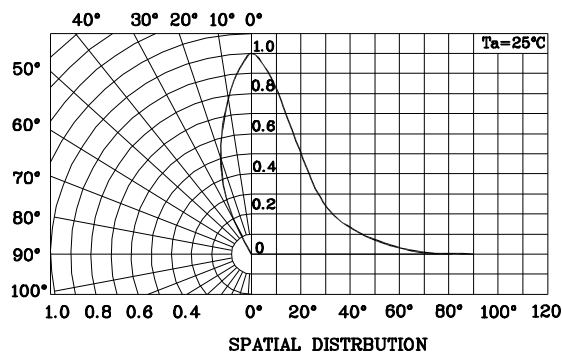
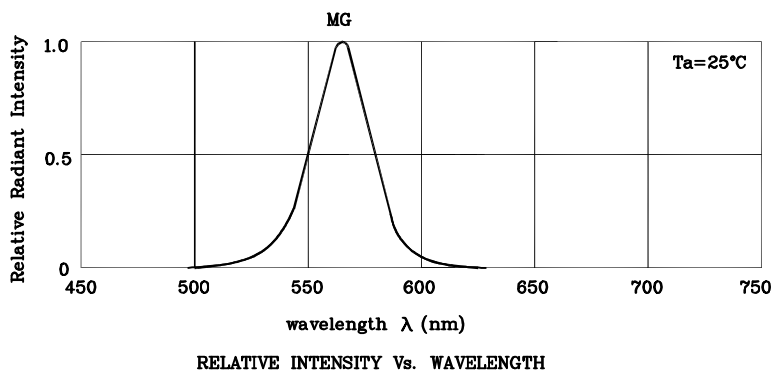
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25 (0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

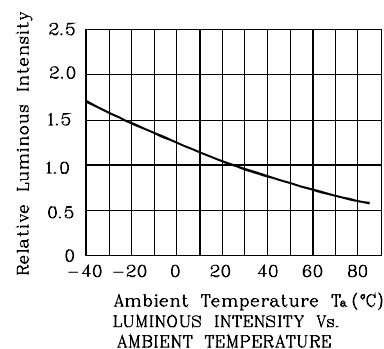
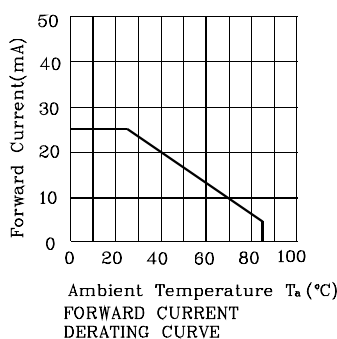
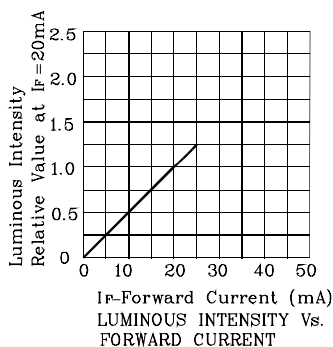
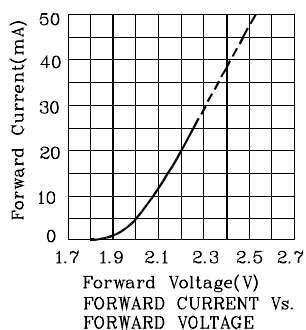
Absolute Maximum Ratings (T _A =25°C)		MG (GaP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	140	mA
Power Dissipation	P _D	62.5	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics ($T_A=25^\circ\text{C}$)		MG (GaP)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	μA
Wavelength of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	565	nm
Wavelength of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	30	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	15	pF

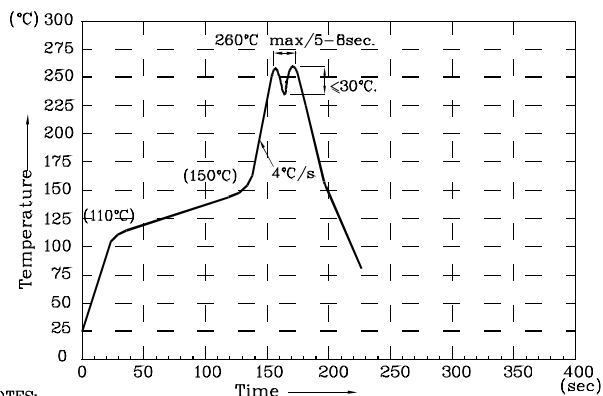
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XNF4ZMG46D	Green	GaP	Green Diffused	8	14	565	40 $^\circ$



❖ MG



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

- 1.Recommend the wave temperature 245 $^\circ\text{C}$ ~260 $^\circ\text{C}$.The maximum soldering temperature should be less than 260 $^\circ\text{C}$.
- 2.Do not apply stress on epoxy resins when temperature is over 85 $^\circ\text{C}$.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105 $^\circ\text{C}$.
- 5.No more than once.

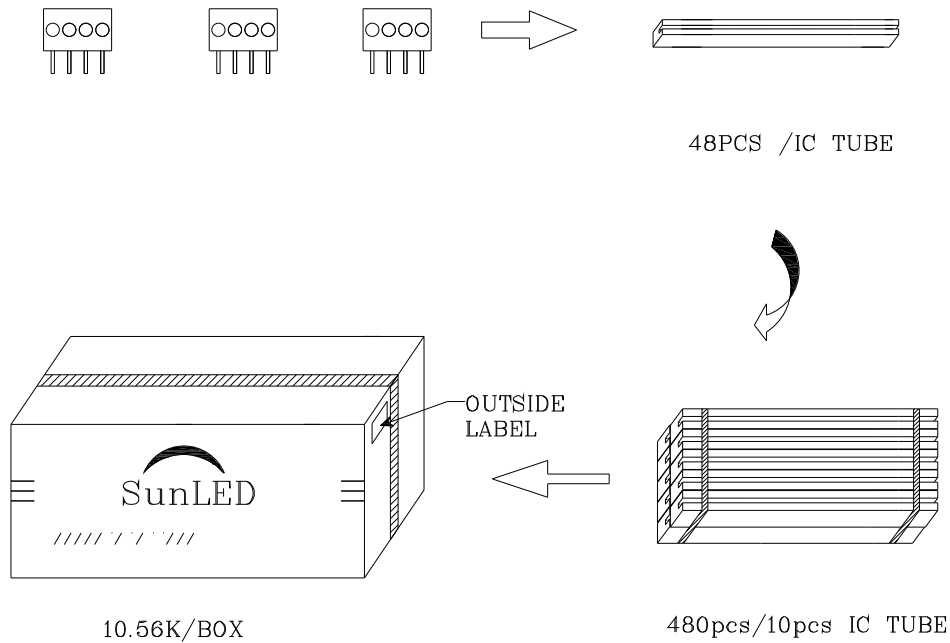
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS





Q.C.
 Q C
 XX XX XXXX
 PASSED

P/NO : XNF4Zxx46x	FQC
QTY : 480 pcs	CODE: XXX
S/N : XX	
LOT NO:  XXXXXXXXXXXXXXXXXXXX RoHS Compliant	